





### SURFACE MOUNT SCHOTTKY BARRIER DIODE

### **Features**

? Low Turn-on Voltage

? Fast Switching

- ? PN Junction Guard Ring for Transient and ESD Protection
- ? Lead Free/RoHS Compliant (Note 3)
- ? " Green " Molding Compound (No Br, Sb) (Note 4)
- ? Qualified to AEC-Q101 Standards for High Reliability

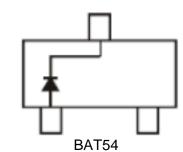
## **Mechanical Data**

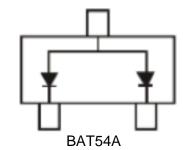
? Case: SOT-23

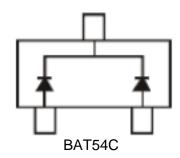
- ? Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- ? Moisture Sensitivity: Level 1 per J-STD-020
- ? Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- ? Polarity: See Diagrams Below
- ? Marking Information: See Page 3
- ? Ordering Information: See Page 2
- ? Weight: 0.008 grams (approximate)

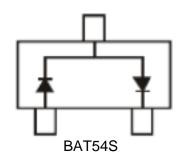


Top View









## **Maximum Ratings**

@T A = 25 ° C unless otherwise specified

Characteristic Symbol			Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	30 V	
Forward Continuous Current (Note 2)		lF	200 mA	
Repetitive Peak Forward Current	·	I <sub>FRM</sub>	300 mA	
Forward Surge Current	@ t < 1.0s	I <sub>FSM</sub>	600 mA	

## **Thermal Characteristics**

Characteristic Symbol		Value	Unit
Power Dissipation (Note 2)	PD	200 mW	
Thermal Resistance, Junction to Ambient Air (Note 2)	R <sub>JA</sub>	500 ° C/W	
Operating and Storage Temperature Range (Note 5)	T J, T STG	-65 to +150	° C

## **Electrical Characteristics**

@T<sub>A</sub> = 25 ° C unless otherwise specified

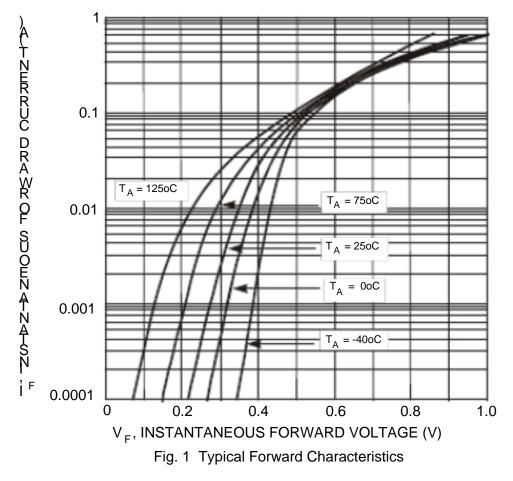
Characteristic Symbol		Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 1)	V <sub>(BR)R</sub>	30	?	?	V	IRS = 100 µA
Forward Voltage	V <sub>F</sub>	?	?	240 320 400 500 800	mV	IF = 0.1mA IF = 1mA IF = 10mA IF = 30mA I <sub>F</sub> = 100mA
Reverse Leakage Current (Note 1)	IR	?	?	2.0	μA	V <sub>R</sub> = 25V
Total Capacitance	Ст	?	?	10 pF		V <sub>R</sub> = 1.0V, f = 1.0MHz
Reverse Recovery Time	t <sub>rr</sub>	?	?	5.0 ns		$I_F = 10$ mA through I $R = 10$ mA to $I_R = 1.0$ mA, R $L = 100$

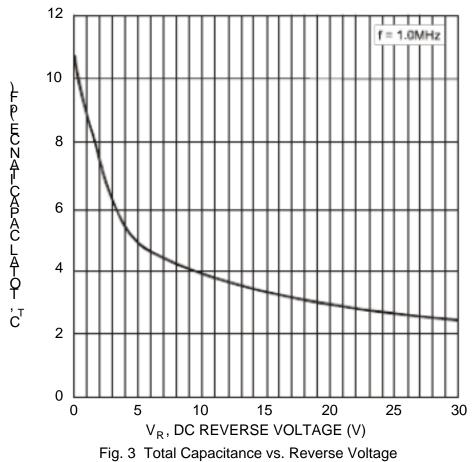
Notes:

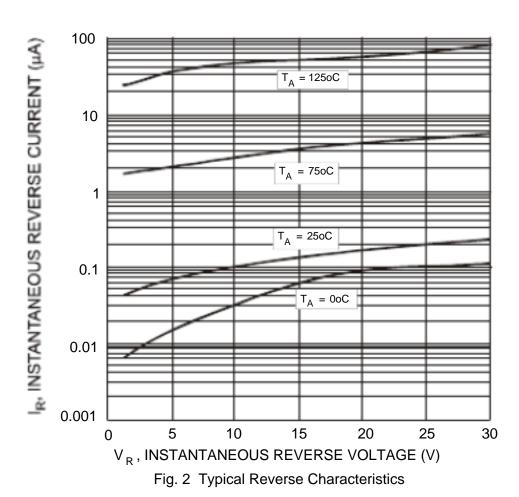
- 1. Short duration test pulse used to minimize self-heating effect.
- Part mounted on FR-4 board with recommended pad layout, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- 3. No purposefully added lead.
- 4. Products manufactured with date code VD (Week 50, 2008) and newer are built with Green Molding Compound. Products manufactured with date code prior to VD are built with Non-Green Molding Compound and may contain Halogens or Sb <sup>2</sup>O<sub>3</sub> Fire Retardants.
- 5. The heat generated must be less than the thermal conductivity from Junction-to-Ambient: dP

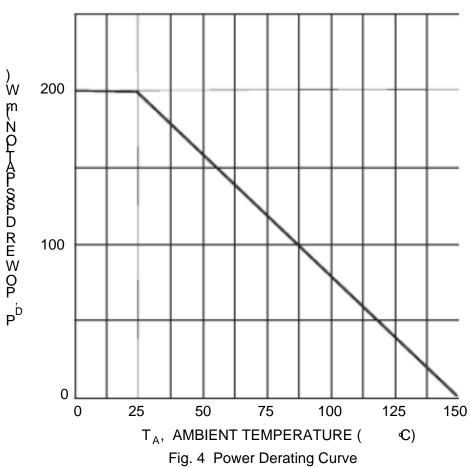
D/dT J < 1/R JA











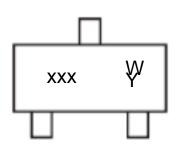
	Ordering	Information	(Note 6)
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Part Number	Case	Packaging
BAT54-7-F	SOT-23	3000/Tape & Reel
BAT54A-7-F	SOT-23	3000/Tape & Reel
BAT54C-7-F	SOT-23	3000/Tape & Reel
BAT54S-7-F	SOT-23	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.



# Marking Information



xxx = Product Type Marking Code

KL1 = BAT54 KL2 = BAT54A

KL3 = BAT54C

KL4 = BAT54S

YM = Date Code Marking

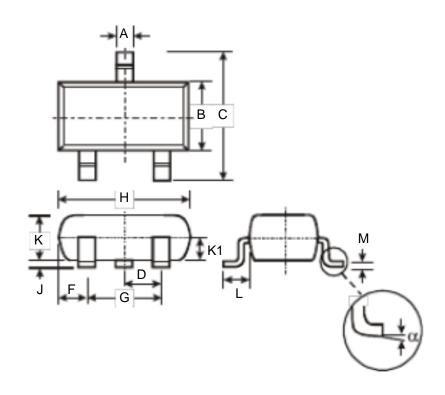
Y = Year (ex: T = 2006)

M = Month (ex: 9 = September)

### Date Code Key

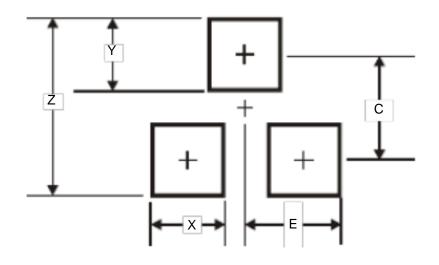
Year	1998 1999	2000 2001 20	02 2003		2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	JKLMN	IPRSTUV	WXYZAE	3 C												
Month	Jan	Feb	Mar	Apr	May		Jun	Jul		Aug	Sep		Oct	Nov		Dec
Code	1234	567								8 9 O				N		D

# Package Outline Dimensions



SOT-23					
Dim Mi	n Max Ty	/p			
Α	0.37 0.	51 0.40			
В	1.20 1.	40 1.30			
С	2.30 2.	50 2.40			
D	0.89 1.	03	0.915		
F	0.45 0.	60	0.535		
G	1.78 2.	05 1.83			
Н	2.80 3.	00 2.90			
J	0.013	0.10 0.	05		
K	0.903	1.10 1.	00		
K1			0.400		
L	0.45 0.	61 0.55			
М	0.085	0.18 0.	11		
	0°8	0	- ]		
All Dimensions in mm					

## Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Y	0.9
С	2.0
F	1 35



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